

REMARKS

Claims 1-5 have been cancelled. Claims 6, 9, and 11 have been amended.

CLAIM REJECTIONS UNDER 35 U.S.C. § 102

Claims 1-9 and 12 stand rejected under 35 USC § 102(b) as being anticipated by U.S. Patent Application No. 2002/00117330 to Eldridge *et al.* ("*Eldridge*"). Applicants request reconsideration of this rejection for at least the following reasons.

As to claims 1-5, claims 1-5 have been cancelled. Therefore, this rejection with regards to claims 1-5 is moot.

As for claim 6, claim 6 has been amended and now includes, among other things, "an interconnect material comprising a conductive material without a wire stem, the interconnect material being coupled directly with the redistributed interconnect; and an interconnect of a second microelectronic die substrate electrically and directly coupled to the interconnect material." Underline added. Applicants respectfully submit that such a structure is not disclosed in *Eldridge*.

In particular, the Examiner in the Office Action cites Figures 32 and 35 as showing each of the limitations of original claim 6. Figure 32 is cited for allegedly showing a microelectronic die substrate (3208) and Figure 35 for allegedly disclosing the contact areas or structures (i.e., redistributed interconnect) as recited in original claim 6. However, neither Figure 32 nor 35, each taken alone or in combination, shows "an interconnect material comprising a conductive material without a wire stem, coupled directly with the redistributed interconnect; and an interconnect of a second microelectronic die substrate electrically coupled directly to the interconnect material." At best *Eldridge* only discloses in Figure 35 a first **printed circuit board (PCB)** 3550 having a plurality of **via holes** coupled to contact areas (i.e., redistributed interconnects) disposed on a surface of the first PCB 3550, the contact areas being coupled to bump-like contact structures (i.e., interconnect material) 3568 **with wire stems** that are indirectly coupled to the contact pads (i.e., interconnects) 3521-3526 of a **second PCB** 3520 **through** resilient contact structures (i.e., wire stems) 3561-3566 and interposer

substrate 3560. Thus, *Eldridge* does not disclose “a conductive interconnect material without a wire stem coupled directly with the redistributed interconnect; and an interconnect of a second microelectronic die substrate electrically coupled directly to the interconnect material.”

Applicants further respectfully disagree with the Examiner’s assertion that *Eldridge* anticipates original claim 1 based on the combination of different elements shown separately in Figures 32 and 35 of *Eldridge*. In particular, the Examiner appears to have selectively pasted together different elements from Figures 32 and 35 in order to come up with the claimed invention as recited in claim 6 even though there appears to be no basis or nexus for doing so. That is, *Eldridge* appears to stand for the proposition that spring-like wire stems coated with overcoat material can be used in interconnecting different electronic components. Figures 32 and 35 simply show how such spring-like wire stems can be used in two different scenarios. The Examiner appears to have cited Figure 32 for the proposition that it shows a microelectronic die substrate while Figure 35 was cited for the proposition that it shows offset contact areas, which in Figure 35, are disposed on a PCB. Applicants submit that there is no motivation or suggestion in either the drawings (Figures 32 or 35) themselves or in the specification of *Eldridge* for combining the microelectronic die substrate of Figure 32 with the offset contact areas of Figure 35, as recited in claim 6. Therefore, for at least the above stated reasons, claim 6 is patentable over *Eldridge*.

Claims 7-9 and 12 each depend upon independent claim 6 incorporating their corresponding limitations. Thus, for at least the above stated reasons, claims 7-9, and 12 are patentable over *Eldridge*.

CLAIM REJECTIONS UNDER 35 U.S.C. § 103

Claim 11 stands rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over *Eldridge*. Claim 11 depends upon amended claim 6, incorporating its limitations. Therefore, by virtue of its dependency, claim 11 is not obvious and is patentable over *Eldridge*.

CONCLUSION

In view of the foregoing, Applicants respectfully submit that claims 6-9, 11, and 12 are in a condition for allowance. Early issuance of Notice of Allowance is respectfully requested.

If the Examiner has any questions, she is invited to contact the undersigned at 503-796-2099.

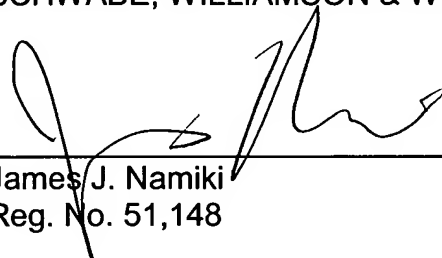
The Commissioner is hereby authorized to charge shortages or credit overpayments to Deposit Account No. 500393.

Respectfully submitted,

SCHWABE, WILLIAMSON & WYATT, P.C.

Dated: _____

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James J. Namiki
Reg. No. 51,148

Pacwest Center, Suite 1900
1211 SW Fifth Avenue
Portland, Oregon 97204
Telephone: (503)222-9981